

HMB-E200

2U Compute Sled for HTCA-E400

PRELIMINARY



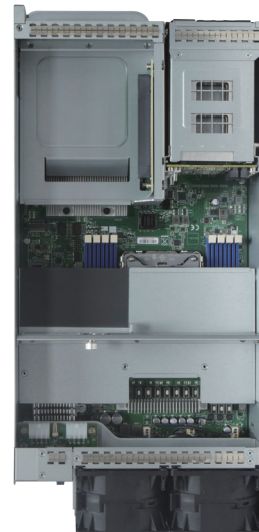
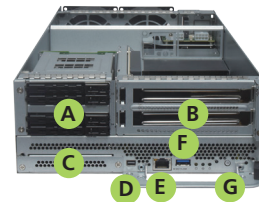
■ Features

- Support 3rd Gen Intel Xeon Scalable Processor (codenamed Ice lake)
- Front Access I/O: Storage bays x4, PCIe x1, NIC slot x1, mini-DP port (VGA signal), LOM and USB 3.0 ports
- Support FH3/4L double width or single width PCIe Card
- Support OCP NIC 3.0 Modules
- Compatible with HTCA-E400 Series

■ Preliminary Specifications

Model	HMB-E200A
Processor	3rd Gen Intel Xeon Scalable Processor (codenamed Ice lake)
Memory	DDR4 DIMM x8, LRDIMM+ECC Max capacity Dependent on CPU
Front Panel Interface	Storage bays x4, PCIe slot x2, OCP NIC slot x1, mini-DP port (VGA signal), LOM and USB 3.0 ports
System Compatibility	HTCA-E400 Series
Temperature	
Operating	0 ~ 40°C
Storage	-40~70°C
Humidity	
	5%~90%. non-condensing
Mechanical	
Dimension (W x H x D)	216.5 x 85 x 490.2 mm
Weight	TBD
Certification	
CE	Class A
FCC	Class A

■ Product I/O View



- A** Storage bays
- B** PCIe slot
- C** OCP NIC slot
- D** Mini-DP port (VGA signal)
- E** LOM port
- F** USB 3.0 port
- G** Power button

■ Ordering Information

HMB-E200A 2U Compute Sled for HTCA-E400

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